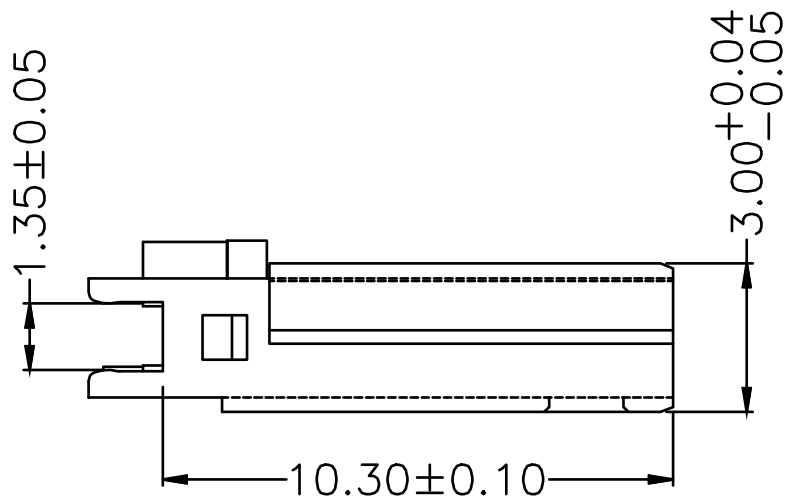
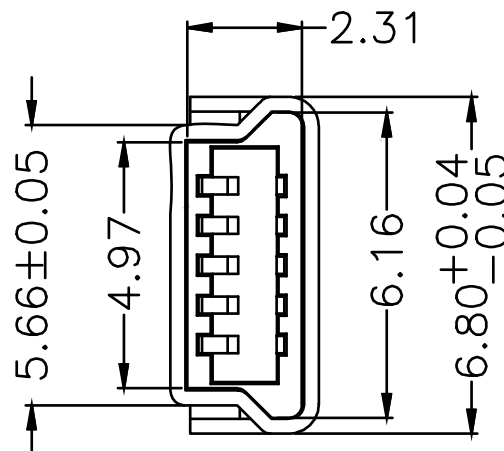
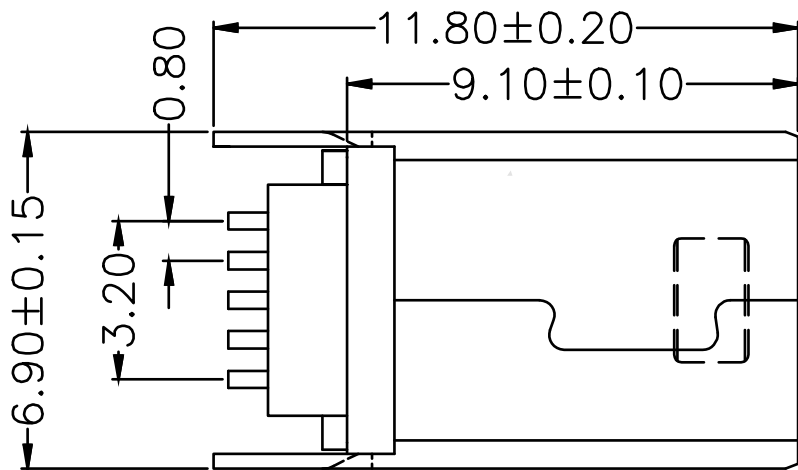


HSF



Specifications:

Current Rating: 1A Max
 Contact Resistance: 50 milliohms MAX
 Dielectric Withstanding Voltage: 100V AC AT Sea Level
 Insulation Resistance: 500 MEGA ohms MIN
 Housing: Temperature Thermoplastics, LCP +30%GF UL 94V-0
 Contact: Copper Alloy
 T=0.25mm Plated Gold in Mating Area;
 Tin On Solder Talls
 Shell: Copper Alloy T=0.40mm Nickel/Plating

Ordering Code:

MUSB - X - P - X - X - X
 ① ② ③ ④ ⑤ ⑥

- ① Series No:
- ② Shell Material:
B:Brass I:Iron
S:stainless steel
- ③ Insulator Material:
P:LCP+30%GF
- ④ Contact Material:
B:Brass
P:Phosphor copper
- ⑤ Contact Plating
G0: Gold flash
G1: 3u" Gold
G2: 5u" Gold
G3: 10u" Gold
G4: 15u" Gold
G5: 30u" Gold
- ⑥ Packing
A:Tray
B:Bag
C:Tube
D:Tape & Reel

Seconn International Enterprise Co., Ltd.

TOLERANCES			PROJECTION	TITLE			
x.	= ± 0.35			Mini USB 10 Pin Male Short Type Connector			
x.x	= ± 0.25						
x.xx	= ± 0.20						
x.xxx	= ± 0.15						
			UNIT				
			mm				
DRAWN	HUA	DATE	2019/12/06	PART NO.	MUSB-XXXXX		
SCALE	NONE	SIZE	A4	SHEET	1/1	REV	A